



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD80R750P7		<b>Issued</b>		25. January 2018		
<b>MA#</b>		MA001652278						
<b>Package</b>		PG-TO252-3-342		<b>Weight*</b>		333.99 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.170	0.65	0.65	6498	6498
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		144	
	non noble metal	iron	7439-89-6	0.160	0.05		480	
	non noble metal	copper	7440-50-8	160.096	47.93	47.99	479347	479971
	non noble metal	aluminium	7429-90-5	0.450	0.13	0.13	1347	1347
wire	non noble metal	aluminium	7429-90-5	0.450	0.13	0.13	1347	1347
encapsulation	organic material	carbon black	1333-86-4	1.163	0.35		3483	
	plastics	epoxy resin	-	16.288	4.88		48768	
	inorganic material	silicondioxide	60676-86-0	127.975	38.32	43.55	383173	435424
leadfinish	non noble metal	tin	7440-31-5	3.740	1.12	1.12	11198	11198
plating	non noble metal	nickel	7440-02-0	0.523	0.16	0.16	1567	1567
solder	non noble metal	tin	7440-31-5	0.043	0.01		130	
	noble metal	silver	7440-22-4	0.054	0.02		163	
	non noble metal	lead	7439-92-1	2.073	0.62	0.65	6208	6501
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		17	
	non noble metal	iron	7439-89-6	0.019	0.01		57	
	non noble metal	copper	7440-50-8	19.177	5.74	5.75	57420	57494
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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